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Electronic Patent Application Submission
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EFS ID: 53693

Application ID: 10667227



Title of Invention:

SEMICONDUCTOR PACKAGE AND
METHOD OF MAKING
LEADFRAME HAVING LEAD
LOCKS TO SECURE LEADS TO
ENCAPSULANT

First Named Inventor: Jae Yee

Domestic/Foreign Application: Domestic Application

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Statement

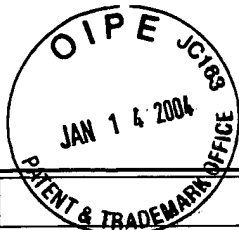
Filing Type:

Confirmation number: 7012

Attorney Docket Number: AMKOR012G1

Total Fees Authorized:


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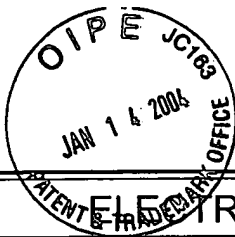


TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT									
Application Number: 10/667227 										
Date: 2003-09-18										
First Named Applicant: Jae Hak Yee										
Confirmation Number: 7012										
Attorney Docket Number: AMKOR012G1										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids4-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids4-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE AND METHOD OF MAKING LEADFRAME HAVING LEAD LOCKS TO SECURE LEADS TO ENCAPSULANT
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Application Number: 10/667227
Confirmation Number: 7012
First Named Applicant: Jae Yee
Attorney Docket Number: AMKOR012G1
Art Unit: 2812



Search string: (5903049 or 5909053 or 5917242 or 5915998
or 5939779 or 5942794 or 5951305 or 5959356
or 5969426 or 5973388 or 5977630 or 5977615
or 5977613 or 5976912 or 5981314 or 5986885
or 5986333 or 6001671 or 6013947 or 6018189
or 6020625 or 6025640 or 6031279 or 6034423
or RE36613 or 6040626 or 6043430 or 6060769
or 6060768 or 6072228 or 6075284 or 6081029
or 6084310 or 6087722 or 6087715 or 6100594
or 6113474 or 6118184 or 6118174 or RE36907
or 6130473 or 6130115 or 6133623 or 6140154
or 6143981 or 6169329 or 6177718 or 6181002
or 6184573 or 6184465).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	5909053	1999-06-01	FUKASE ET AL.			
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	48	6181002	2001-01-30	JUSO ET AL
	49	6184573	2001-02-06	PU
	50	6184465	2001-02-06	CORISIS

Signature

Examiner Name	Date